SN54192, SN54193, SN54LS192, SN54LS193, SN74192, SN74193, SN74LS192, SN74LS193 SYNCHRONOUS 4-BIT UP/DOWN COUNTERS (DUAL CLOCK WITH CLEAR)

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- Cascading Circuitry Provided Internally
- Synchronous Operation
- Individual Preset to Each Flip-Flop
- Fully Independent Clear Input

TYPES	TYPICAL MAXIMUM	TYPICAL
	COUNT FREQUENCY	POWER DISSIPATION
192,193	32 MHz	325 mW

'LS192,'LS193

32 MHz 32 MHz 325 mW 95 mW

description

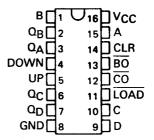
These monolithic circuits are synchronous reversible (up/down) counters having a complexity of 55 equivalent gates. The '192 and 'LS192 circuits are BCD counters and the '193 and 'LS193 are 4-bit binary counters. Synchronous operation is provided by having all flip-flops clocked simultaneously so that the outputs change coincidently with each other when so instructed by the steering logic. This mode of operation eliminates the output counting spikes which are normally associated with asynchronous (ripple-clock) counters.

The outputs of the four master-slave flip-flops are triggered by a low-to-high-level transition of either count (clock) input. The direction of counting is determined by which count input is pulsed while the other count input is high.

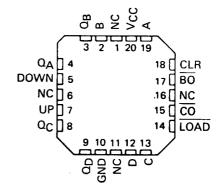
All four counters are fully programmable; that is, each output may be preset to either level by entering the desired data at the data inputs while the load input is low. The output will change to agree with the data inputs independently of the count pulses. This feature

SN54192, SN54193, SN54LS192, SN54LS193 . . . J OR W PACKAGE SN74192, SN74193 . . . N PACKAGE SN74LS192, SN74LS193 . . . D OR N PACKAGE

(TOP VIEW)



SN54LS192, SN54LS193 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

allows the counters to be used as modulo-N dividers by simply modifying the count length with the preset inputs.

A clear input has been provided which forces all outputs to the low level when a high level is applied. The clear function is independent of the count and load inputs. The clear, count, and load inputs are buffered to lower the drive requirements. This reduces the number of clock drivers, etc., required for long words.

These counters were designed to be cascaded without the need for external circuitry. Both borrow and carry outputs are available to cascade both the up- and down-counting functions. The borrow output produces a pulse equal in width to the count-down input when the counter underflows. Similarly, the carry output produces a pulse equal in width to the count-up input when an overflow condition exists. The counters can then be easily cascaded by feeding the borrow and carry outputs to the count-down and count-up inputs respectively of the succeeding counter.

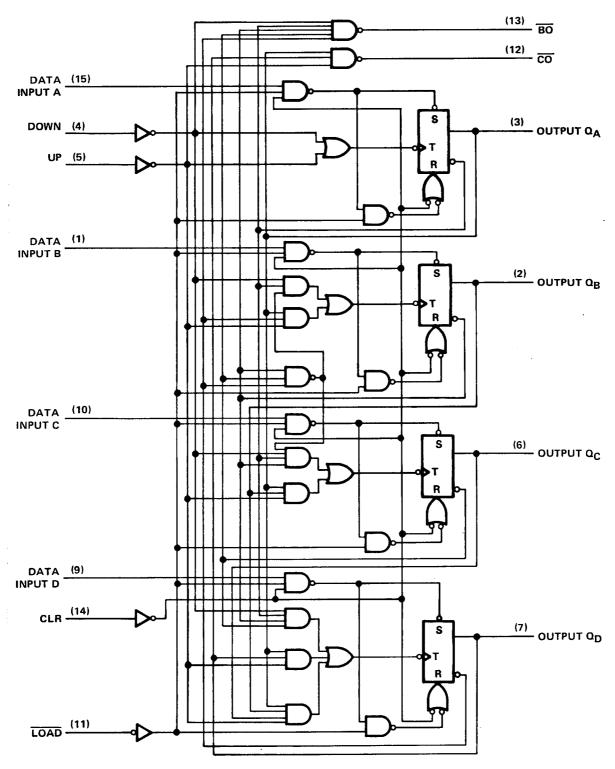
absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

	SN54'	SN54LS'	SN74'	SN74LS'	UNIT
Supply voltage, V _{CC} (see Note 1)	7	7	7	7	V
Input voltage	5.5	7	5.5	7	V
Operating free-air temperature range	- 55	to 125	0	to 70	°C
Storage temperature range	-65	to 150	- 65	to 150	°C

NOTE 1: Voltage values are with respect to network ground terminal.



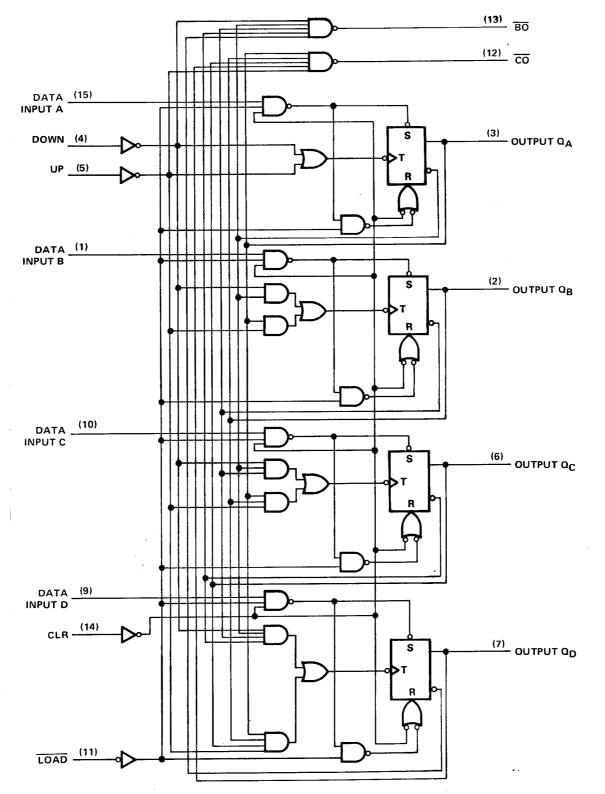
logic diagram (positive logic)



Pin numbers shown are for D, J, N, and W packages.



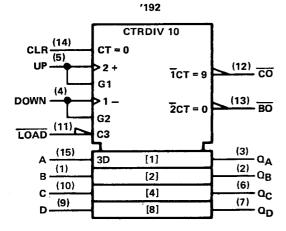
logic diagram (positive logic)

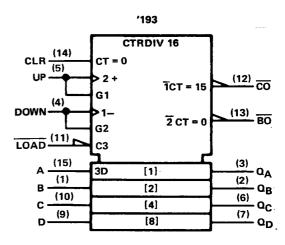


Pin numbers shown are for D, J, N, and W packages.



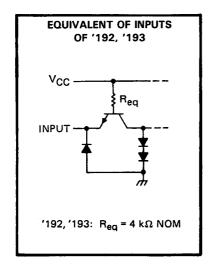
logic symbols†

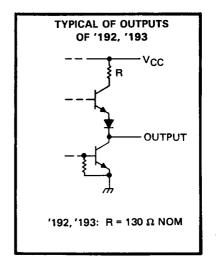


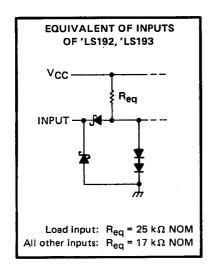


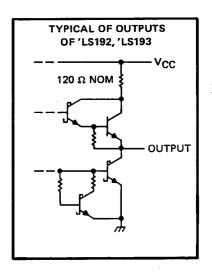
 † These symbols are in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12. Pin numbers shown are for D, J, N, and W packages.

schematics of inputs and outputs









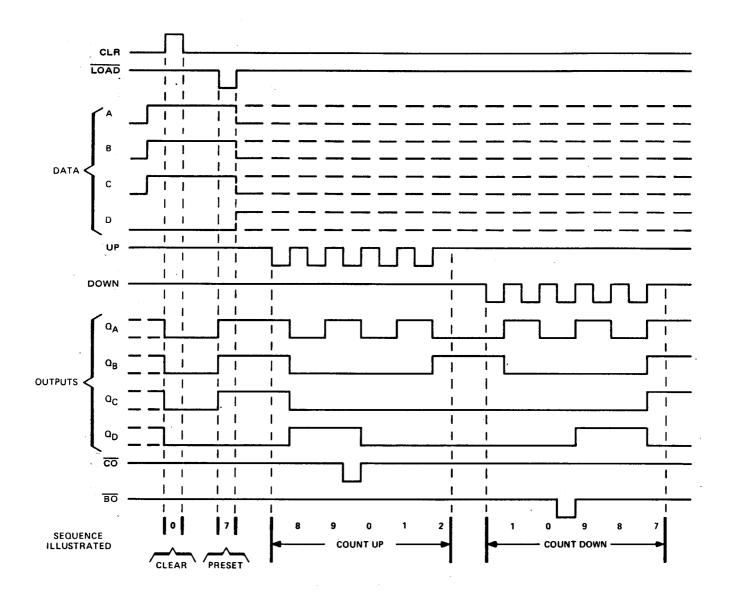


'192, 'LS192 DECADE COUNTERS

typical clear, load, and count sequences

Illustrated below is the following sequence:

- 1. Clear outputs to zero.
- 2. Load (preset) to BCD seven.
- 3. Count up to eight, nine, carry, zero, one, and two.
- 4. Count down to one, zero, borrow, nine, eight, and seven.



NOTES: A. Clear overrides load, data, and count inputs.

B. When counting up, count-down input must be high; when counting down, count-up input must be high.

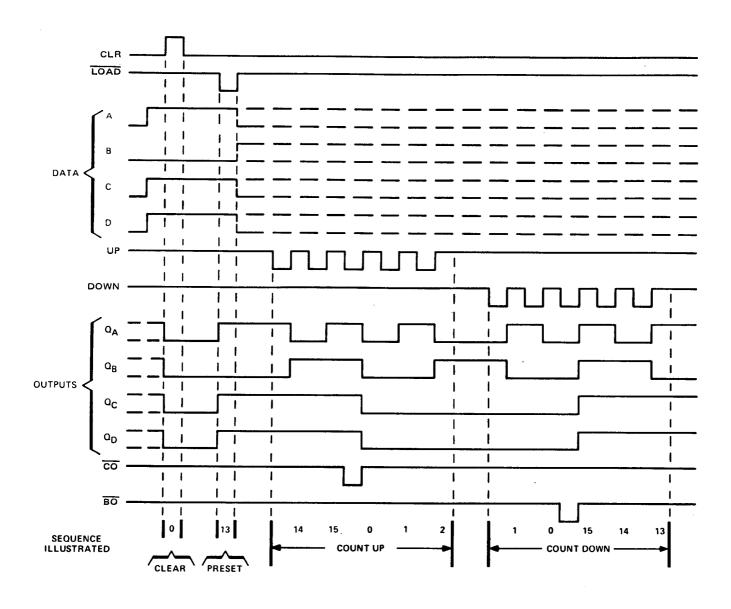


'193, 'LS193 BINARY COUNTERS

typical clear, load, and count sequences

Illustrated below is the following sequence:

- 1. Clear outputs to zero.
- 2. Load (preset) to binary thirteen.
- 3. Count up to fourteen, fifteen, carry, zero, one, and two.
- 4. Count down to one, zero, borrow, fifteen, fourteen, and thirteen.



NOTES: A. Clear overrides load, data, and count inputs.

B. When counting up, count-down input must be high; when counting down, count-up input must be high.



recommended operating conditions

			1	SN5419 SN5419		l .	SN7419 SN7419		UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
Vcc	Supply voltage		4.5	5	5.5	4.75	5	5.25	V
Гон	High-level output current				-0.4			-0.4	mA
loL	Low-level output current	w-level output current					_	16	mA
fclock	Clock frequency		0		25	0		25	MHz
tw	Width of any input pulse		20			20			ns
t _{su}	Data setup time, (see Figure 1)		20			20			ns
		Data, high or low	0	-		0			
th	Hold time	LOAD	3			3			ns
TA	Operating free-air temperature		-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CONDITIONS [†]		SN5419 SN5419			UNIT		
			MIN	TYP‡	MAX	MIN	TYP‡	MAX	
ViH	High-level input voltage		2			2			V
VIL	Low-level input voltage				8.0			0.8	V
VIK	Input clamp voltage	V _{CC} = MIN, I _I = -12 mA			-1.5			-1.5	V
Voн	High-level output voltage	V _{CC} = MIN, V _{IH} = 2 V, V _{IL} = 0.8 V, I _{OH} = -0.4 mA	2.4	3.4		2.4	3.4		V
VOL	Low-level output voltage	V _{CC} = MIN, V _{IH} = 2 V V _{IL} = 0.8 V, I _{OL} = 16 mA		0.2	0.4		0.2	0.4	v
11	Input current at maximum input voltage	V _{CC} = MAX, V _I = 5.5 V			1			1	mA
ΊΗ	High-level input current	V _{CC} = MAX, V _I = 2.4 V			40			40	μА
liL.	Low-level input current	V _{CC} = MAX, V ₁ = 0.4 V			-1.6			-1.6	mA
los	Short-circuit output current§	V _{CC} = MAX	-20		-65	-18		-65	mA
Icc	Supply current	V _{CC} = MAX, See Note 2		65	89		65	102	mA

[†]For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type. ‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.

NOTE 2: I_{CC} is measured with all outputs open, clear and load inputs grounded, and all other inputs at 4.5 V.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ} \text{ C}$

PARAMETER¶	FROM INPUT	TO OUTPUT	TEST CONDITIONS	MIN	TYP	MAX	UNIT
f _{max}				25	32		MHz
^t PLH	110	CO	7		17	26	
[†] PHL	UP	CO			16	24	ns
tPLH .	DOWN	BO	CL = 15 pF,		16	24	
tPHL	DOWN	ВО	$R_L = 400 \Omega$,		16	24	ns
^t PLH	UP OR DOWN	Q	See Figures 1 and 2		25	38	
^t PHL .	T OF OR DOWN	· ·	See Figures Fand 2		31	47	ns
t _{PLH}					27	40	
[‡] PHL	LOAD	Q			29	40	ns
^t PHL	CLR	Q			22	35	ns

 $[\]P_{f_{max}} \equiv maximum \ clock \ frequency$

tpHL = propagation delay time, high-to-low-level output



[§] Not more than one output should be shorted at a time.

tpLH = propagation delay time, low-to-high-level output

SN54LS192, SN54LS193, SN74LS192, SN74LS193 SYNCHRONOUS 4-BIT UP/DOWN COUNTERS (DUAL CLOCK WITH CLEAR)

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recommended operating conditions

			N54LS19 N54LS19			N74LS1	-	UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
Vcc	Supply voltage	4.5	. 5	5.5	4.75	5	5.25	V
IOH	High-level output current			-400			-400	μΑ
loL	Low-level output current			4			8	mA
fclock	Clock frequency	0		25	0		25	MHz
tw	Width of any input pulse	20	***************************************		20			ns
	Clear inactive-state setup time	15			15			ns
t _{su}	Load inactive-state setup time	15			15			ns
	Data setup time (see Figure 1)	20			20			ns
th	Data hold time	5			5			ns
TA	Operating free-air temperature range	-55		125	0		70	°c

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TE	ST CONDITIONS	şt		N54LS1 N54LS1		s S	UNIŢ		
			٠.		MIN	TYP [‡]	MAX	MIN	TYP‡	MAX	l
V_{IH}	High-level input voltage				2			2			V
VIL	Low-level input voltage						0.7			0.8	V
VIK	Input clamp voltage	V _{CC} = MIN,	I _I = -18 mA				-1.5			-1.5	V
Voн	High-level output voltage	V _{CC} = MIN, V _{IL} = V _{IL} max	V _{IH} = 2 V, , I _{OH} = -400 μΑ		2.5	3.4		2.7	3.4		V
VOL	Low-level output voltage	V _{CC} = MIN, V _{IL} = V _{IL} max	V _{IH} = 2 V,	I _{OL} = 4 mA		0.25	0.4		0.15 0.35	0.4 0.5	V
IJ	Input current at maximum input voltage	V _{CC} = MAX,	V _i = 7 V				0.1			0.1	;mA
ΉΗ	High-level input current	V _{CC} = MAX,	V _I = 2.7 V				20			20	μА
ηL	Low-level input current	V _{CC} = MAX,	V _I = 0.4 V				-0.4			-0.4	mA
los	Short-circuit output current §	V _{CC} = MAX			-20		-100	-20		-100	mA
Icc	Supply current	V _{CC} = MAX,	See Note 2			19	∤34		19	-34	mA

[†]For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type. ‡All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25 ^{\circ} \text{C}$.

NOTE 2: I_{CC} is measured with all outputs open, clear and load inputs grounded, and all other inputs at 4.5 V.

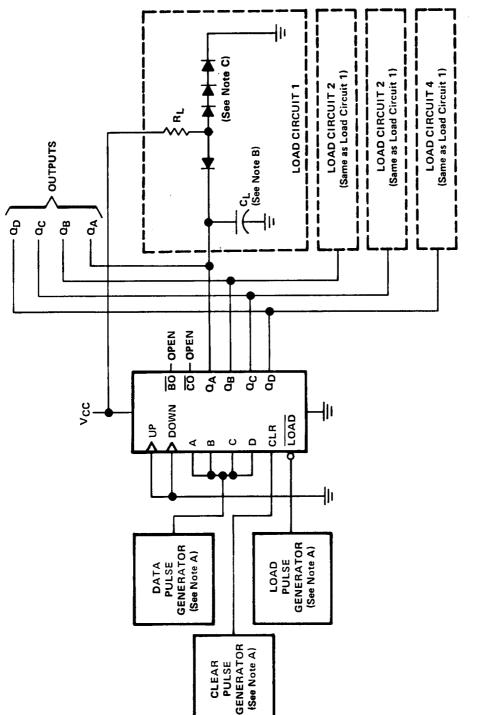
switching characteristics, VCC = 5 V, TA = 25°C

PARAMETER	FROM INPUT	TO OUTPU T	TEST CONDITIONS	MIN	TYP	MAX	UNIT
f _{max}				25	32		MHz
^t PLH	UP	CO			17	26	ns
tPHL] Ur				18	24	113
^t PLH	DOWN	BO	C _L = 15 pF,		16	24	ns
tPHL	DOWN	во	$R_L = 2 k\Omega$,		15	24	113
^t PLH	UR OR ROWN	Q	See Figures 1 and 2		27	38	
tPHL	UP OR DOWN	u	See Figures Fand 2		30	47	ns
^t PLH	1040				24	40	
t _{PHL}	LOAD	Q			25	40	ns
tPHL	CLR	Q			23	35	ns



[§] Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.

PARAMETER MEASUREMENT INFORMATION



TEST CIRCUIT

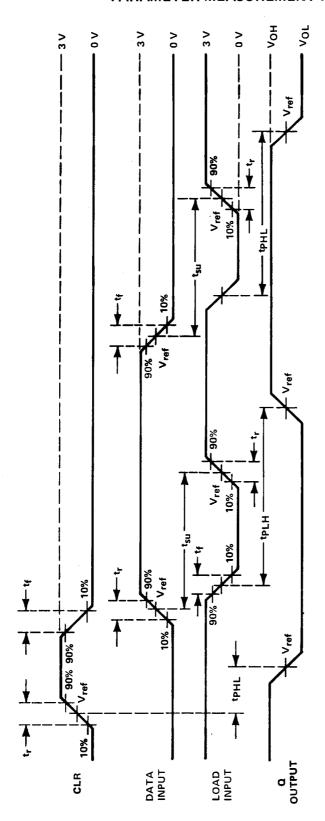
The pulse generators have the following characteristics: Z_{out} ≈ 50 Ω and for the data pulse generator PRR ≤ 500 kHz, duty cycle = 50%; for the load pulse generator PRR is two times data PRR, duty cycle = 50% Ä NOTES:

- C_L includes probe and jig capacitance. Diodes are 1N3064 or equivalent.
- t_r and $t_f \le 7$ ns. <u>க</u>் ப் ப் ய
- Vref is 1.5 V for '192 and '193, 1.3 V for 'LS192 and 'LS193.

FIGURE 1A - CLEAR, SETUP AND LOAD TIMES



PARAMETER MEASUREMENT INFORMATION



VOLTAGE WAVEFORMS

NOTES: A. The pulse generators have the following characteristics: Z_{out} ≈ 50 Ω and for the data pulse generator PRR ≤ 500 kHz, duty cycle = 50%; for the load pulse generator PRR is two times data PRR, duty cycle = 50%

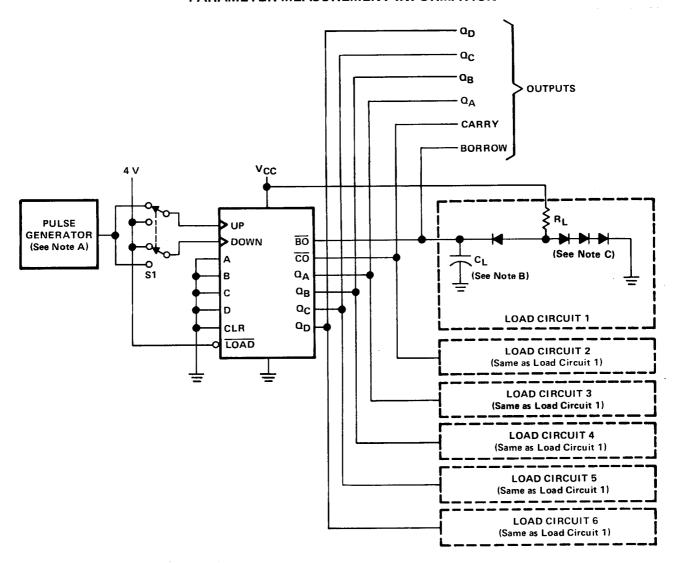
- CL includes probe and jig capacitance.
 - Diodes are 1N3064 or equivalent.
- V_{ref} is 1.5 V for '192 and '193, 1.3 V for 'LS192 and 'LS193. ほいり 豆

FIGURE 18 - CLEAR, SETUP, AND LOAD TIMES



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PARAMETER MEASUREMENT INFORMATION



TEST CIRCUIT

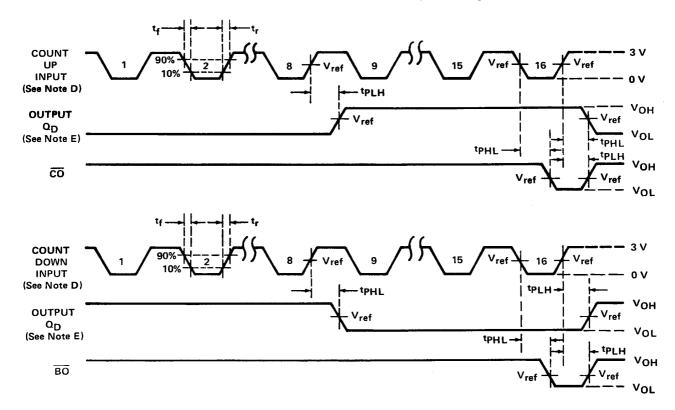
NOTES: A. The pulse generators have the following characteristics: PRR \approx 1 MHz, Z_{out} \approx 50 Ω , duty cycle = 50%.

- B. C_L includes probe and jig capacitance.
- C. Diodes are 1N3064 or equivalent.
- D. Cout-up and dount-down pulse shown are for the '193 and 'LS193 binary counters. Count cycle for '192 and 'LS192 decade counters is 1 through 10.
- E. Waveforms for outputs Q_A , Q_B , and Q_C are omitted to simplify the drawing.
- F. t_r and $t_f \le 7$ ns.
- G. V_{ref} is 1.5 V for '192 and '193, 1.3 V for 'LS192 and 'LS193.

FIGURE 2A - PROPAGATION DELAY TIMES



PARAMETER MEASUREMENT INFORMATION



VOLTAGE WAVEFORMS

NOTES: A. The pulse generators have the following characteristics: PRR \approx 1 MHz, Z_{out} \approx 50 Ω , duty cycle = 50%.

- B. C_L includes probe and jig capacitance.
- C. Diodes are 1N3064 or equivalent.
- D. Cout-up and dount-down pulse shown are for the '193 and 'LS193 binary counters. Count cycle for '192 and 'LS192 decade counters is 1 through 10.
- E. Waveforms for outputs Q_A , Q_B , and Q_C are omitted to simplify the drawing.
- F. t_r and $t_f \le 7$ ns.
- G. V_{ref} is 1.5 V for '192 and '193, 1.3 V for 'LS192 and 'LS193.

FIGURE 2B - PROPAGATION DELAY TIMES





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PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)				•	(2)		(3)		(4/5)	
5962-9558401QEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9558401QE A SNJ54192J	Samples
5000 0550 404054	4.OTI) (F	055		40			A 40	N / A / DI T	55 / 105		
5962-9558401QFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9558401QF A	Samples
										SNJ54192W	_
5962-9558401QFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9558401QF A SNJ54192W	Samples
76006012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	76006012A SNJ54LS 193FK	Samples
76006012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	76006012A SNJ54LS 193FK	Samples
7600601EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7600601EA SNJ54LS193J	Samples
7600601EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7600601EA SNJ54LS193J	Samples
7600601FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7600601FA SNJ54LS193W	Samples
7600601FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7600601FA SNJ54LS193W	Samples
JM38510/01309BEA	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	-55 to 125		
JM38510/01309BEA	OBSOLETE		J	16		TBD	Call TI	Call TI	-55 to 125		
JM38510/31508B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 31508B2A	Samples
JM38510/31508B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 31508B2A	Samples
JM38510/31508BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 31508BEA	Samples
JM38510/31508BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 31508BEA	Samples
JM38510/31508BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 31508BFA	Samples





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Orderable Device	Status	Package Type	_	Pins	_	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)		(3)		(4/5)	
JM38510/31508BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 31508BFA	Samples
JM38510/31508SEA	ACTIVE	CDIP	J	16	25	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 31508SEA	Samples
JM38510/31508SEA	ACTIVE	CDIP	J	16	25	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 31508SEA	Samples
JM38510/31508SFA	ACTIVE	CFP	W	16	25	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 31508SFA	Samples
JM38510/31508SFA	ACTIVE	CFP	W	16	25	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 31508SFA	Samples
M38510/31508B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 31508B2A	Samples
M38510/31508B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 31508B2A	Samples
M38510/31508BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 31508BEA	Samples
M38510/31508BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 31508BEA	Samples
M38510/31508BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 31508BFA	Samples
M38510/31508BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 31508BFA	Samples
M38510/31508SEA	ACTIVE	CDIP	J	16	25	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 31508SEA	Samples
M38510/31508SEA	ACTIVE	CDIP	J	16	25	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 31508SEA	Samples
M38510/31508SFA	ACTIVE	CFP	W	16	25	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 31508SFA	Samples
M38510/31508SFA	ACTIVE	CFP	W	16	25	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 31508SFA	Samples
SN54192J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54192J	Samples
SN54192J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54192J	Samples
SN54193J	OBSOLET	E CDIP	J	16		TBD	Call TI	Call TI	-55 to 125		
SN54193J	OBSOLET	E CDIP	J	16		TBD	Call TI	Call TI	-55 to 125		





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Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN54LS193J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS193J	Samples
SN54LS193J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS193J	Samples
SN74192N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74192N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74193N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74193N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74193N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74193N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74LS192D	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI	0 to 70		
SN74LS192D	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI	0 to 70		
SN74LS192N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74LS192N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74LS193D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS193	Samples
SN74LS193D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS193	Samples
SN74LS193DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS193	Samples
SN74LS193DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS193	Samples
SN74LS193DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS193	Samples
SN74LS193DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS193	Samples
SN74LS193DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS193	Samples
SN74LS193DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS193	Samples
SN74LS193DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS193	Samples
SN74LS193DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS193	Samples



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Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Sample
SN74LS193DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS193	Sample
SN74LS193DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS193	Sample
SN74LS193J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	0 to 70		
SN74LS193J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	0 to 70		
SN74LS193N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS193N	Sample
SN74LS193N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS193N	Sample
SN74LS193N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74LS193N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74LS193NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS193N	Sample
SN74LS193NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS193N	Sample
SN74LS193NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS193	Sample
SN74LS193NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS193	Sample
SN74LS193NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS193	Sample
SN74LS193NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS193	Sample
SN74LS193NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS193	Sample
SN74LS193NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS193	Sample
SNJ54192J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9558401QE A SNJ54192J	Sample
SNJ54192J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9558401QE A SNJ54192J	Sample
SNJ54192W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9558401QF A	Sample





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Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Diaming		٦.,	(2)		(3)		(4/5) SNJ54192W	
SNJ54192W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9558401QF A SNJ54192W	Samples
SNJ54193J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	-55 to 125		
SNJ54193J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	-55 to 125		
SNJ54193W	OBSOLETE	CFP	W	16		TBD	Call TI	Call TI	-55 to 125		
SNJ54193W	OBSOLETE	CFP	W	16		TBD	Call TI	Call TI	-55 to 125		
SNJ54LS193FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	76006012A SNJ54LS 193FK	Samples
SNJ54LS193FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	76006012A SNJ54LS 193FK	Samples
SNJ54LS193J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7600601EA SNJ54LS193J	Samples
SNJ54LS193J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7600601EA SNJ54LS193J	Samples
SNJ54LS193W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7600601FA SNJ54LS193W	Samples
SNJ54LS193W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7600601FA SNJ54LS193W	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.





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Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- (3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

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OTHER QUALIFIED VERSIONS OF SN54192, SN54193, SN54LS193, SN54LS193-SP, SN74192, SN74193, SN74LS193:

Catalog: SN74192, SN74193, SN74LS193, SN54LS193

• Military: SN54192, SN54193, SN54LS193

Space: SN54LS193-SP

NOTE: Qualified Version Definitions:

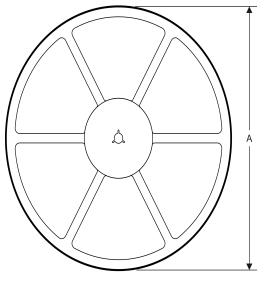
- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications
- Space Radiation tolerant, ceramic packaging and qualified for use in Space-based application

PACKAGE MATERIALS INFORMATION

14-Jul-2012 www.ti.com

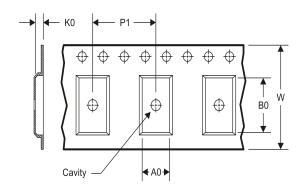
TAPE AND REEL INFORMATION

REEL DIMENSIONS





TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

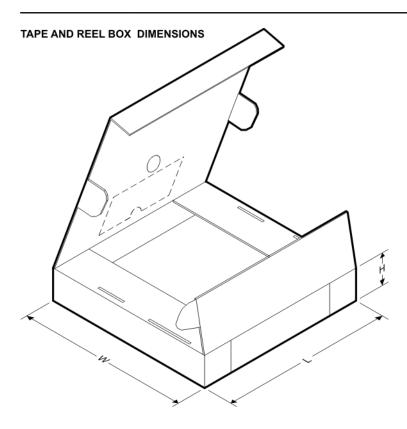
TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS193DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LS193NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

PACKAGE MATERIALS INFORMATION

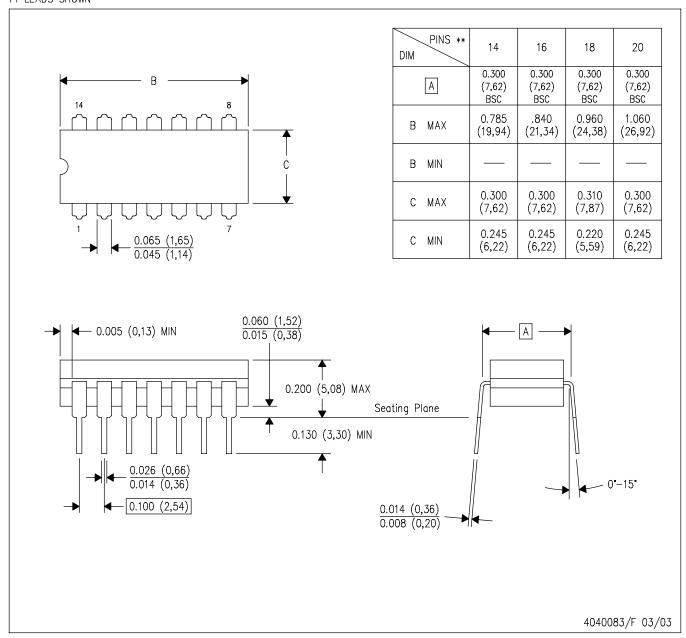
www.ti.com 14-Jul-2012



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS193DR	SOIC	D	16	2500	333.2	345.9	28.6
SN74LS193NSR	SO	NS	16	2000	367.0	367.0	38.0

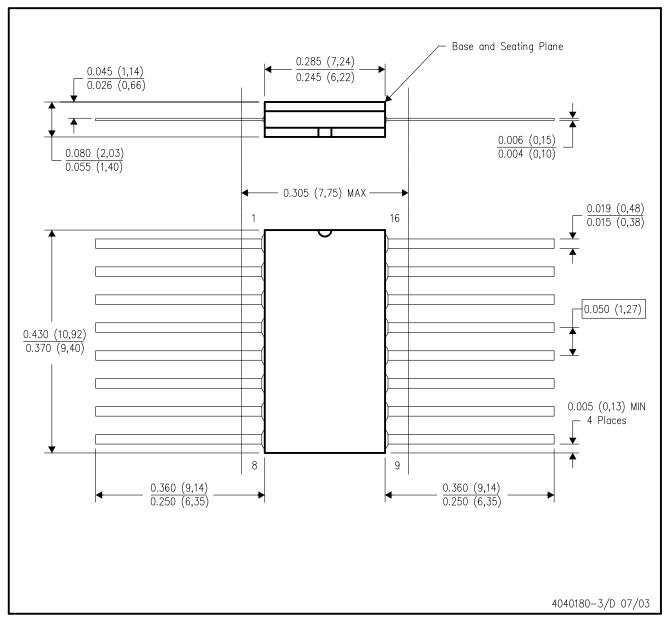
14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



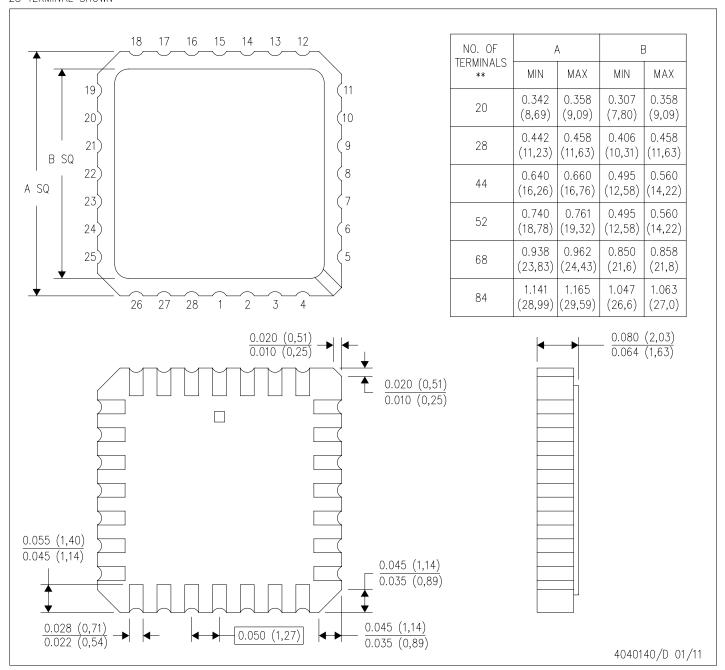
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F16 and JEDEC MO-092AC



FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

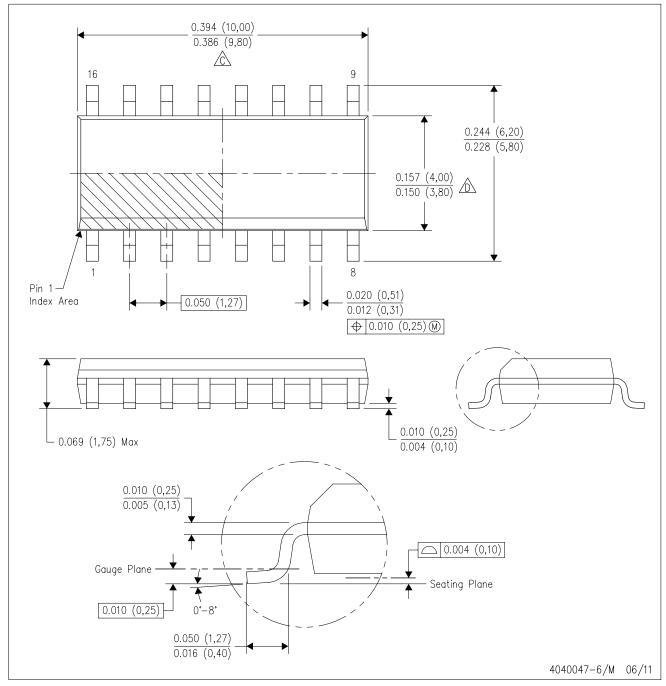


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDS0-G16)

PLASTIC SMALL OUTLINE

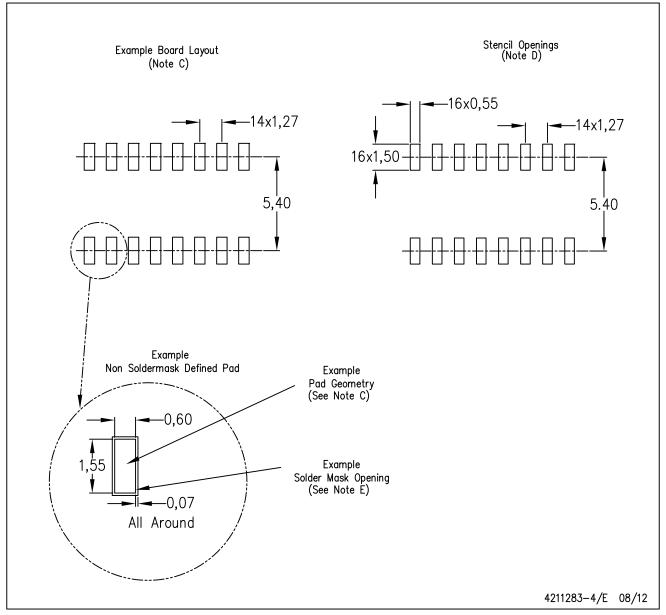


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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